GSM1362XF

Preliminary Specification

100V N-Channel MOSFETs

Absolute Maximum Ratings (TJ=25°C Unless otherwise specified)

Symbol	Parameter		Value	Unit	
V _{DSS}	Drain-Source Voltage		100	V	
V _{GSS}	Gate-Source Voltage		±20	V	
	Continuous Drain Current (Silicon Limited)	T _C =25°C	105	A	
I _D		T _C =100°C	66		
	Continuous Drain Current (Package Limited)		80		
I _{DM}	Pulsed Drain Current ¹		320	Α	
las	Single Pulse Avalanche Current, L = 0.1mH ²		25	Α	
Eas	Single Pulse Avalanche Energy, L = 0.1mH ²		62.5	mJ	
Б	Power Dissipation	T _C =25°C	125	W	
P _D		T _C =100°C	50		
$R_{ heta JC}$	Thermal Resistance-Junction to Case		1	°C/W	
R _{eJA}	Thermal Resistance-Junction to Ambient		62	°C/W	
TJ	Operating Junction Temperature Range		-55 to +150	°C	
T _{STG}	Storage Temperature Range		-55 to +150	°C	

NOTE:

Electrical Characteristics (T_J=25°C Unless otherwise specified)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
	Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100			V	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =100V, V _{GS} =0V			1	uA	
I _{GSS}	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =±20V			±100	nA	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1.2		2.5	V	
R _{DS(on)}	Dunin Course On Besistenes	V _{GS} =10V, I _D =15A			6.2		
	Drain-Source On-Resistance	V _{GS} =4.5V, I _D =10A			8.5	8.5 mΩ	
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A			1	V	
gfs	Forward Transconductance	V _{DS} =5V, I _D =30A	-	42	-	S	



^{1.} Single pulse width is limited by max junction temperature.

Packages & Pin Assignments

DFN5X6-8L			Equivalent Circuit		
	1 2 3 4		G S		
Pin	Symbol	Description	Pin	Symbol	Description
1	S	Source	8	D	Drain
2	S	Source	7	D	Drain
3	S	Source	6	D	Drain
4	G	Gate	5	D	Drain



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